

# LNPT<sup>TM</sup> THERMOCOMP<sup>TM</sup> COMPOUND LF006E

LF-1006 EM  
REGION AMERICAS

## DESCRIPTION

LNP THERMOCOMP LF006E compound is based on Polyetheretherketone (PEEK) resin containing 30% glass fiber. Added features of this grade include: Easy Molding.

GENERAL INFORMATION	
Features	Good Processability, High stiffness /Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyetheretherketone (PEEK)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Consumer	Commercial Appliance
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

## TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL <sup>(1)</sup></b>			
Tensile Stress, break	181	MPa	ASTM D638
Tensile Strain, break	2	%	ASTM D638
Tensile Modulus, 5 mm/min	13030	MPa	ASTM D638
Flexural Stress	262	MPa	ASTM D790
Flexural modulus	11030	MPa	ASTM D790
Tensile Stress, break	187	MPa	ISO 527
Tensile Strain, break	2	%	ISO 527
Tensile Modulus, 1 mm/min	12900	MPa	ISO 527
Flexural Stress	278	MPa	ISO 178
Flexural Modulus	12500	MPa	ISO 178
<b>IMPACT <sup>(1)</sup></b>			
Izod Impact, unnotched, 23°C	913	J/m	ASTM D4812
Izod Impact, notched, 23°C	117	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	8	J	ASTM D3763
Izod Impact, unnotched 80°10°4 +23°C	58	kJ/m <sup>2</sup>	ISO 180/1U
Izod Impact, notched 80°10°4 +23°C	11	kJ/m <sup>2</sup>	ISO 180/1A
<b>THERMAL <sup>(1)</sup></b>			
HDT, 0.45 MPa, 3.2 mm, unannealed	>298	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	>298	°C	ASTM D648
CTE, -40°C to 40°C, flow	1.98E-05	1/°C	ASTM E831

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -40°C to 40°C, xflow	3.6E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, flow	2.05E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	3.62E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	>240	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	>240	°C	ISO 75/Af
<b>PHYSICAL <sup>(1)</sup></b>			
Density	1.53	g/cm <sup>3</sup>	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.08	%	ASTM D570
Density	1.53	g/cm <sup>3</sup>	ISO 1183
<b>INJECTION MOLDING <sup>(2)</sup></b>			
Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Front - Zone 3 Temperature	380 – 400	°C	
Middle - Zone 2 Temperature	380 – 400	°C	
Rear - Zone 1 Temperature	370 – 380	°C	
Mold Temperature	175 – 190	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

## ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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